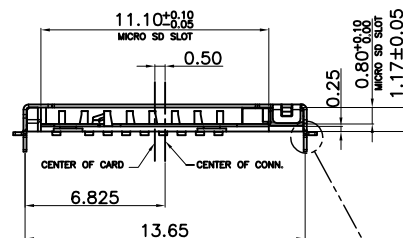
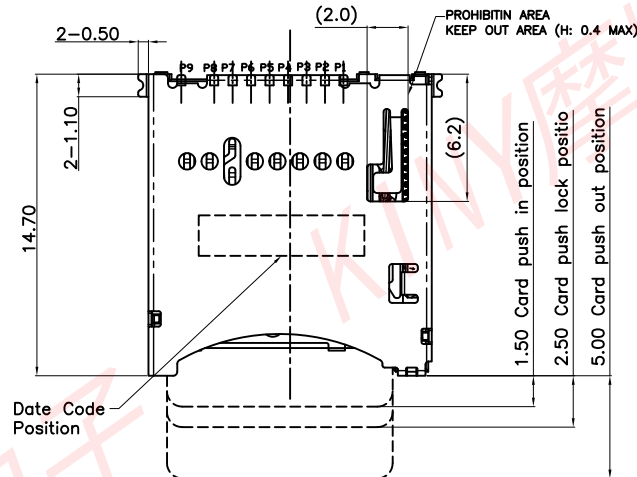
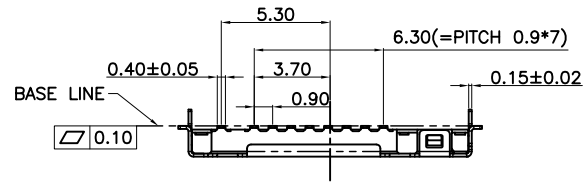
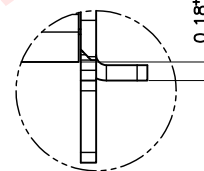
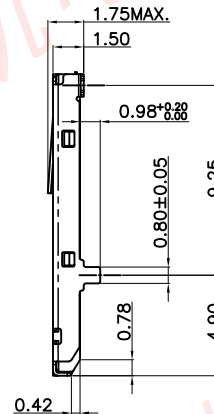


* 所有原材料, 生产制程, 电镀必须符合HF要求

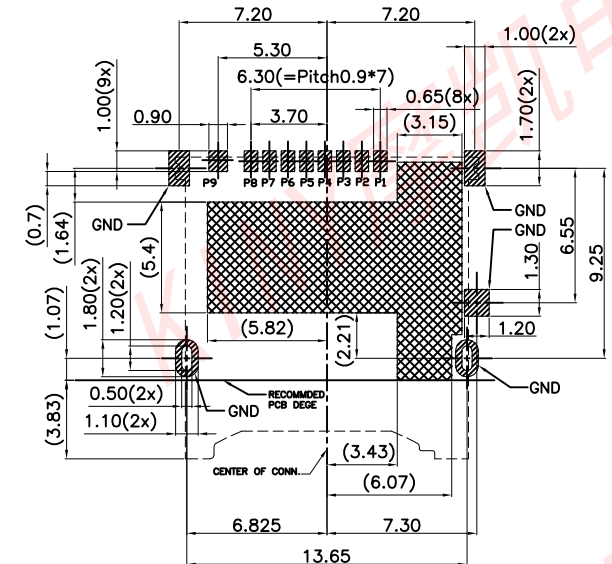
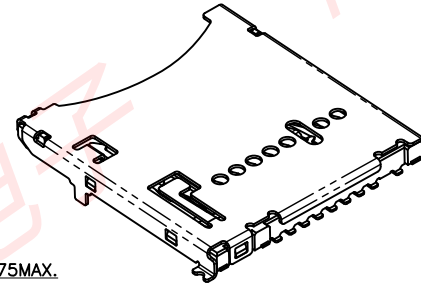


Pin Define	
P1	DAT2
P2	CD/DAT3
P3	CMD
P4	VDD
P5	CLK
P6	VSS
P7	DAT0
P8	DAT1
P9	CD

COMPOSITION OF DETECTION	
CARD DETECT(SW)	
P6	CD(P9)
CARD DETECTION/SWITCH	
CARD INSTALLATION:ON	
NON CARD:OFF	
WHEN BECOMIOG SW ON CARD INSTALLATION	



Detail A
Scale 5 : 1



PAD AREA

No trace , no test point,
no via hole, no ground area

PCB PATTERN LAYOUT
(GENERAL TOLERANCE:±0.05)

Specification

*Electrical Characteristics:

Contact Current Rating:0.5Amperes.

Dielectric Withstanding Voltage:AC500V r.m.s.

Insulation Resistance:1000 Megohms

Minimum At DC 500V.

Contact Resistance:100 mΩ Maximum.

*Mechanical Characteristics:

Mating Cycles:10,000 Cycles.

*Environmental:

Operating Temperature:-25°C~+85°C.

*Materials:

Insulator:HI-Temp plastic (LCP,S475),UL Black 94V-0.

Contact:Phosphor Bronze(C5210-EH,T=0.10±0.03mm)

Shell:SUS304-1/2H T=0.15±0.03mm

*Plating:

Contact: Plated 50u"min Ni Overall

Plated 1u"min Au Selective Contact Area

Plated 80u"min Sn over Ni on solder area

Shell: Plated 50u"min Ni Overall

KINY

东莞市摩凯电子有限公司

DIMENSIONS INIT: mm
UNLESS OTHERWISE SPECIFIABLE

DIMENSION	TOLERANCE
X.X: ±	0.35
X.XX: ±	0.20
X.XXX: ±	0.10
ANGULAR: ±	2°

PRODUCT NAME : Micro SD P-P板上H=1.50mm(QH)	DRAWING: PURE	DATE: 2019.08.31
PRODUCT NO. : MC150-T1251-11	CHECK: Alex	DATE: 2019.08.31
DRAWING NO. : D-MC150-T1251-11	APPROVED: Alex	DATE: 2019.08.31
SCALE: 1:1	DWG ID: C D	REV.: B
		PAGE: 1 of 1

B	ECN20190902001	变更料号增加外壳SMT脚刷金GOLD FLASH	PURE	2019.08.31
A	----	NEW RELEASE	Janyz	2019.08.21
REVISION NO.	ECR NO.	DESCRIPTION	MARK	DATE